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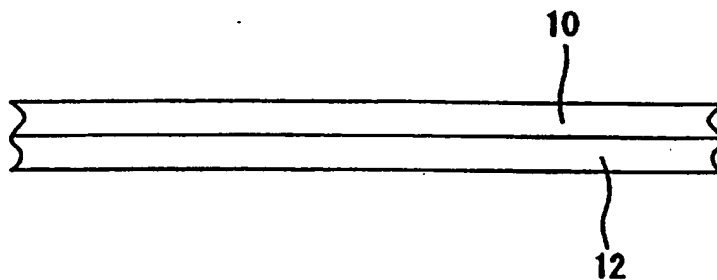
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(54) **Thin film, method for manufacturing thin film, and electronic component**

(57) A method for manufacturing a thin film (10) is performed such that the internal stress is controlled while the preferred orientation property is maintained at a high value. An AlN piezoelectric thin film is formed on

a substrate (12) by a sputtering method using a mixed gas including Ar and nitrogen, wherein the mixed gas has a nitrogen flow rate ratio, that is, nitrogen flow rate relative to the sum of the Ar flow rate and the nitrogen flow rate, of about 10% to about 75%.

FIG. 1



EP 1 174 525 A2

Description

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0001] The present invention relates to a thin film, a method for manufacturing the thin film, and an electronic component. More particularly, the present invention relates to a thin film, for example, a piezoelectric material thin film, a dielectric material thin film, and a magnetic material thin film, or other suitable thin film, used for an electronic component, for example, a piezoelectric thin film resonator, a filter, sensor, and an actuator or other suitable device.

2. Description of the Related Art

[0002] Since a resonant frequency of a piezoelectric resonator using a thickness longitudinal vibration of a piezoelectric substrate is inversely proportional to the thickness of the piezoelectric substrate, in the superhigh frequency regions, the piezoelectric substrate must be processed extensively to be very thin. Regarding the decrease in the thickness of the piezoelectric substrate itself, however, in the fundamental mode, several 100 MHz have been believed to be the practical limit of the high frequency due to the mechanical strength and restrictions in the handling thereof.

[0003] In order to solve the aforementioned problems, diaphragm type piezoelectric thin film resonators have been suggested, and have been used for filters and resonators. Fig. 5 is a sectional schematic diagram of an example of a conventional piezoelectric thin film resonator. The piezoelectric thin film resonator 1 as shown in Fig. 5 includes a Si substrate 2. A thin film support member 3 having a thickness of several μm or less is formed on the substrate 2 by a partial etching from the reverse surface using a micromachining method. An AlN piezoelectric thin film 5 is provided on the thin film support member 3 as a piezoelectric material thin film including a lower layer electrode 4a and an upper layer electrode 4b on both major surfaces as a pair of excitation electrodes. The thin film support member 3 and peripheral portions thereof thereby define a diaphragm 6. In the piezoelectric thin film resonator 1 as shown in Fig. 5, the thin film support member 3 can be formed to be thin using the micromachining technique, and the AlN piezoelectric thin film 5 can be also formed to be thin by the sputtering, or other suitable process, so that the high frequency characteristics may be extended to several 100 MHz to several 1,000 MHz.

[0004] In order to produce resonance characteristics that are superior in the temperature characteristics of the resonant frequency and in the antiresonance characteristics, a piezoelectric thin film resonator as shown in Fig. 6 has been suggested. Fig. 6 is a sectional schematic diagram of another example of a conventional pi-

ezoelectric thin film resonator. When the piezoelectric thin film resonator 7 as shown in Fig. 6 is compared with the piezoelectric thin film resonator 1 as shown in Fig. 5, a thin film 8 made of SiO_2 , Si_3N_4 , Al_2O_3 , or ZnO , is formed as the upper layer of the Si substrate 2.

[0005] In order to realize the piezoelectric thin film resonators 1 and 7 as shown in Fig. 5 and Fig. 6, the stress of the entire device must be controlled so as not to destroy the diaphragm 6. Since the thin film of SiO_2 has strong compressibility, the thin films of Si_3N_4 and Al_2O_3 have a strong tensile property, and so forth, the internal stress of the AlN piezoelectric thin film 5 must be controlled.

[0006] It is said that in order that excellent piezoelectricity to be achieved in the AlN piezoelectric thin film, the C axis is preferably oriented in the direction that is perpendicular to the substrate, and the half-width of the rocking curve is preferably small, as described in, for example, "Acoustic Wave Technology Handbook" written by the Japan Society for the Promotion of Science, 150th Committee on Acoustic Wave Technology issued by Ohmsha, Ltd., 1991. In general, in the case in which the AlN piezoelectric thin film is formed by the sputtering method, an excellent C axis preferred orientation film is produced at a low gas pressure region, that is, at a film generating a pressure of 0.6 Pa or less, as described in, for example, J. Mater. Res., Vol. 12, No. 7, p. 1850 (1997) by A. Rodriguez-Navarro, W. Otano-Rivera, J. M. Garcia-Ruiz, R. Messier, and L. J. Pilione. On the other hand, since the peening effect is strong at the low gas pressure region, the formed AlN piezoelectric thin film has strong compressibility. Therefore, the internal stress of the AlN piezoelectric thin film has previously been controlled with the gas pressure during the film formation.

[0007] When the gas pressure during the film formation is increased, however, the preferred orientation property of the AlN piezoelectric thin film is reduced, and accompanying this, the resonance characteristic is also reduced. As a consequence, the internal stress of the AlN piezoelectric thin film controlled by the gas pressure and the preferred orientation property have a trade-off relationship, so that controlling the internal stress while keeping the preferred orientation property high was not possible.

SUMMARY OF THE INVENTION

[0008] In order to overcome the problems described above, preferred embodiments of the present invention provide a thin film and method of manufacturing the same, in which the internal stress is controlled while the preferred orientation property is kept high.

[0009] Also, other preferred embodiments of the present invention provide an electronic component including a thin film in which the internal stress is controlled while the preferred orientation property is kept high.

[0010] According to a preferred embodiment of the

present invention, a thin film primarily including AlN formed on a surface of a substrate is provided, in which the crystallinity is the C axis preferred orientation, the half-width of a rocking curve is about 1.4° to about 1.6°, and an internal stress can be controlled within the range of approximately ± 1 GPa.

[0011] According to another preferred embodiment of the present invention, a method for manufacturing a thin film includes the steps of forming a thin film according to various preferred embodiments of the present invention by a sputtering method using a mixed gas including Ar and nitrogen, wherein the mixed gas has a nitrogen flow rate ratio, that is, a nitrogen flow rate relative to an Ar flow rate and the nitrogen flow rate, of about 10% to about 75%.

[0012] According to another preferred embodiment of the present invention, an electronic component includes a thin film according to preferred embodiments of the present invention.

[0013] Regarding preferred embodiments of the present invention, by controlling the nitrogen flow rate ratio of the mixed gas including Ar and nitrogen used in the sputtering method for forming the thin film, the internal stress of the thin film can be controlled without changing the preferred orientation property of the thin film.

[0014] Therefore, in the case in which the thin film is mounted on, for example, the piezoelectric resonator, even when the internal stress of the thin film is selected so as to decrease warping and cracking, the effect on the resonance characteristics due to the change in the preferred orientation property of the thin film is minimized.

[0015] Other features, elements, characteristics and advantages of the present invention will become apparent from the following detailed explanations of preferred embodiments of the present invention with reference to the drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0016]

Fig. 1 is a sectional schematic diagram of an AlN piezoelectric thin film according to a preferred embodiment of the present invention;

Fig. 2 is a graph showing the dependency of the internal stress of the AlN piezoelectric thin film on the nitrogen flow rate ratio;

Fig. 3 is a graph showing dependency of the C axis preferred orientation of the AlN piezoelectric thin film on the nitrogen flow rate ratio;

Fig. 4 is a sectional schematic diagram of an AlN piezoelectric thin film resonator according to a preferred embodiment of the present invention;

Fig. 5 is a sectional schematic diagram of an example of a conventional piezoelectric thin film resonator; and

Fig. 6 is a sectional schematic diagram of another example of a conventional piezoelectric thin film resonator.

DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS

[0017] Fig. 1 is a sectional schematic diagram of an AlN piezoelectric thin film according to a preferred embodiment of the present invention. An AlN piezoelectric thin film 10 as shown in Fig. 1 is formed on a substrate 12 that is preferably made of, for example, Si or other suitable material. In this case, the AlN piezoelectric thin film 10 is formed preferably using an RF magnetron sputtering apparatus including an Al target and using a mixed gas including Ar and nitrogen. In one example of the present preferred embodiment, the AlN piezoelectric thin film 10 is formed at a temperature of the substrate 12 of approximately 100°C, with an RF power of the apparatus of 100 W, and at a nitrogen flow rate ratio of about 5% to about 90%.

[0018] The dependency of the internal stress and the C axis preferred orientation of the AlN piezoelectric thin film 10, formed as described above, on the nitrogen flow rate ratio are shown in Fig. 2 and Fig. 3 with graphs.

[0019] The internal stress σ was calculated from the relationship represented by Formula 1 among the warp amount δ of the substrate 12 before and after the formation of the AlN piezoelectric thin film 10, the measurement distance L of the warp amount, the film thickness d of the AlN piezoelectric thin film 10, the Young's modulus E of the substrate 12, the thickness t of the substrate 12, and the Poisson ratio p of the substrate 12.

$$\sigma = 4Et^2\delta / 3d(1-p)L^2 \quad \text{Formula 1}$$

[0020] Regarding the C axis preferred orientation, the half-width of the (002) rocking curve of the X-ray diffraction was measured.

[0021] As is clear from the graphs as shown in Fig. 2 and Fig. 3, at the nitrogen flow rate ratio of about 10% to about 75%, the internal stress of the AlN piezoelectric thin film 10 can be controlled within the range of about ± 1 GPa, while the C axis preferred orientation of the AlN piezoelectric thin film 10 is in a high, stable region of about 1.4° to about 1.6°.

[0022] Therefore, in this AlN piezoelectric thin film 10, the internal stress can be controlled, while the C axis preferred orientation is kept high, by controlling the nitrogen flow rate ratio, which is a film formation parameter.

[0023] Fig. 4 is a sectional schematic diagram of an AlN piezoelectric thin film resonator according to another preferred embodiment of the present invention. A piezoelectric thin film resonator 20 as shown in Fig. 4 includes an Si substrate 22.

[0024] On the Si substrate 22, a thin film 24 preferably made of SiO_2 , Si_3N_4 , or Al_2O_3 , or other suitable material, a lower layer electrode 26a, an AlN piezoelectric material thin film 28 primarily including AlN as a piezoelectric thin film, and an upper layer electrode 26b are formed in the aforementioned order. In this case, the thin film 24 is preferably formed over the entire top surface of the Si substrate 22. The lower layer electrode 26a is formed on a portion including the central portion on the top surface of the thin film 24. The AlN piezoelectric thin film 28 is formed on the top surfaces of the thin film 24 and the lower layer electrode 26a corresponding to the portion including the central portion of the thin film 24. The upper layer electrode 26b is formed on the top surface of the AlN piezoelectric thin film 28 corresponding to the portion including the central portion of the thin film 24. In this case, the AlN piezoelectric thin film 28 is preferably formed under the conditions which are the same as those existing when forming the AlN piezoelectric thin film 10 as shown in the aforementioned Fig. 1. Regarding the others, the thin film 24, the lower layer electrode 26a, and the upper layer electrode 26b are formed preferably by sputtering, vapor deposition, or other suitable process.

[0025] A diaphragm 30 is formed on the substrate 22 by removing the portion thereof corresponding to the central portion of the thin film 24 via anisotropic etching, RIE (Reactive Ion Etching), or other suitable process, from the reverse surface thereof.

[0026] In this piezoelectric thin film resonator 20, even when the internal stress of the AlN piezoelectric thin film 28 is controlled to relax the stresses of SiO_2 having strong compressibility and Si_3N_4 , Al_2O_3 , or other suitable material, having strong tensile property, which are used as the thin film 24, since the change in the preferred orientation property of the AlN piezoelectric thin film 28 is small, stable resonance characteristics, in which the electromechanical coupling coefficient k^2 is about 30% or more of the bulk, can be exhibited.

[0027] Furthermore, in this piezoelectric thin film resonator 20, the film thickness ratio of the thin film 24 relative to the AlN piezoelectric thin film 28 may be adjusted to improve the resonance characteristics, such as the temperature characteristics of the resonant frequency, although the adjustment of the warp of the diaphragm 30 due to the change in the film thickness ratio can be controlled with the internal stress of the AlN piezoelectric thin film 28.

[0028] Therefore, in this piezoelectric thin film resonator 20, even when the internal stress of the AlN piezoelectric thin film 28 is controlled to minimize the warp of the diaphragm part 30, change in the resonance characteristics can be substantially eliminated.

[0029] The present invention can be applied to not only the piezoelectric material thin films, but also to other thin films, such as dielectric material thin films and magnetic material thin films, and other thin films.

[0030] In addition, the present invention can be ap-

plied to piezoelectric thin film resonators as described above, but the present invention can also be applied to other electronic components, such as filters, sensors, and actuators.

[0031] According to the present invention, the internal stress can be controlled while the preferred orientation property is kept high in the thin films, for example, the piezoelectric material thin films, used for the electronic components, for example, the piezoelectric thin film resonators.

[0032] While the present invention has been particularly shown and described with reference to preferred embodiments thereof, it will be understood by those skilled in the art that the foregoing and other changes in form and details can be made without departing from the spirit and scope of the invention.

Claims

1. A thin film (10; 28) comprising:
an AlN material provided on a surface of a substrate (12; 22), wherein the crystallinity is the C axis preferred orientation, the half-width of a rocking curve is about 1.4° to about 1.6° , and an internal stress is within the range of approximately ± 1 GPa.
2. The thin film according to claim 1, wherein the thin film (10; 28) is one of a piezoelectric thin film, a dielectric thin film and a magnetic material thin film.
3. An electronic component (20) comprising:
a substrate (22); and
a thin film (28) disposed on the substrate (22) and made of an AlN material, wherein the crystallinity is the C axis preferred orientation, the half-width of a rocking curve is about 1.4° to about 1.6° , and an internal stress is within the range of approximately ± 1 GPa.
4. The electronic component (20) according to claim 3, wherein the substrate (22) is made of Si.
5. The electronic component (20) according to claims 3 or 4, further comprising a thin film (24) made of one SiO_2 , Si_3N_4 , and Al_2O_3 , a lower layer electrode (26a), the thin film (28), and an upper layer electrode (26b) arranged in this order.
6. The electronic component (20) according to one of claims 3 to 5, wherein a diaphragm (30) is provided on the substrate (22).
7. The electronic component (20) according to one of claims 3 to 6, wherein the electronic component (20) is one of a piezoelectric thin film resonator, a filter, a sensor, and an actuator.

8. A method for manufacturing a thin film (10; 28) comprising the steps of:

providing a substrate (12; 22); and
forming a thin film (10; 28) on the substrate (12; 22) using a mixed gas of Ar and nitrogen such that the thin film (10; 28) includes an AlN material, wherein the crystallinity is the C axis preferred orientation, the half-width of a rocking curve is about 1.4° to about 1.6°, and an internal stress is within the range of approximately ± 1 GPa;

wherein said mixed gas has a nitrogen flow rate ratio of about 10% to about 75%, wherein the nitrogen flow rate is a ratio of a nitrogen flow rate relative to the sum of an Ar flow rate and the nitrogen flow rate.

9. The method according to claim 8, wherein the thin film (10; 28) is formed via a sputtering process.
10. The method according to claim 8 or 9, wherein the AlN piezoelectric thin film (10; 28) is formed at a temperature of the substrate (12; 22) of approximately 100°C, with an RF power of about 100 W, and at a nitrogen flow rate ratio of about 5% to about 90%.
11. The method according to claim 8, wherein the thin film (10; 28) is one of a piezoelectric thin film, a dielectric thin film and a magnetic material thin film.
12. The method according to claim 8, wherein the substrate (12; 22) is made of Si.
13. The method according to claim 8, further comprising the steps of forming a thin film (24) made of one SiO₂, Si₃N₄, and Al₂O₃, a lower layer electrode (26a), forming the thin film (28), and an upper layer electrode (26b) arranged in this order.
14. The method according to claim 8, further comprising the step of forming a diaphragm (30) on the substrate (12; 22).
15. An electronic component (20) comprising a thin film (28) manufactured according to the method of Claim 8.
16. The electronic component (20) according to claim 15, wherein the electronic component (20) is one of a piezoelectric thin film resonator, a filter, a sensor, and an actuator.

FIG. 1

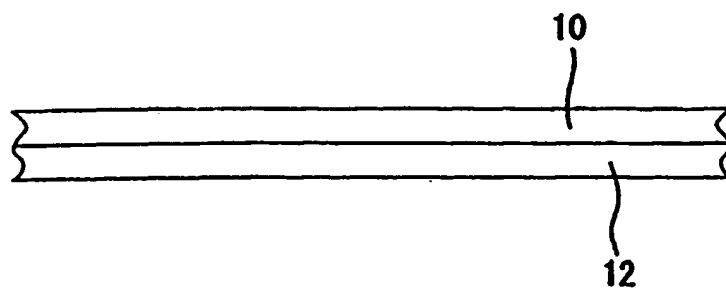


FIG. 2

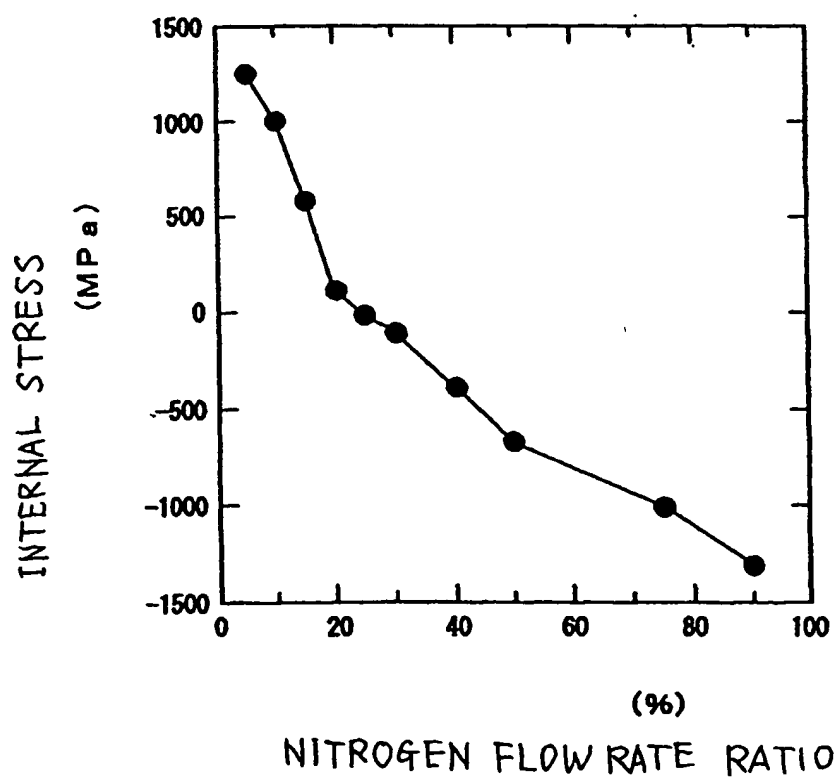


FIG. 3

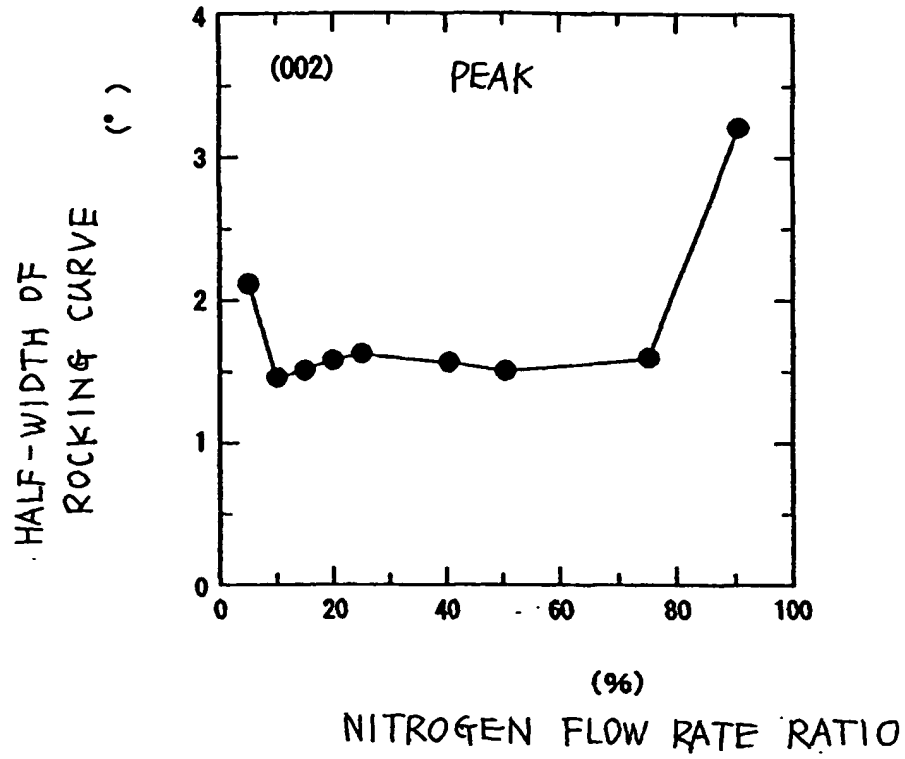


FIG. 4

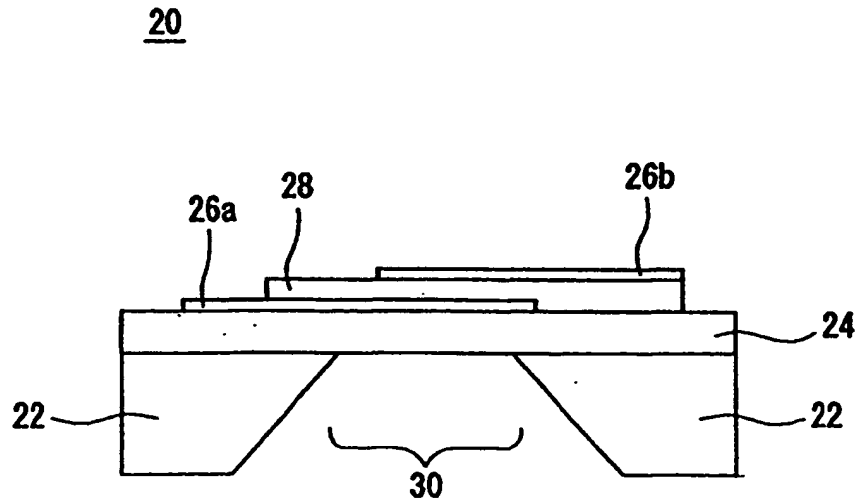


FIG. 5

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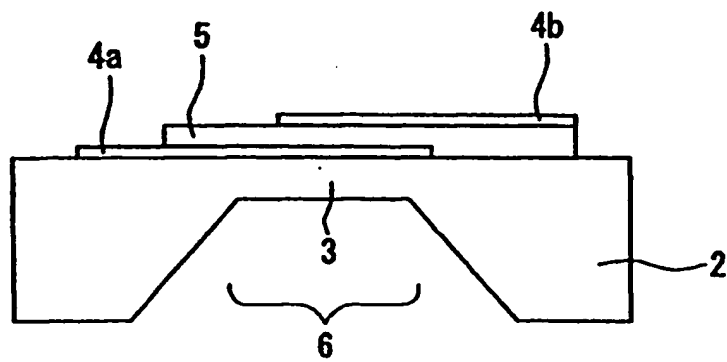


FIG. 6

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